

## HSC285

Silicon Schottky Barrier Diode for High frequency detection

REJ03G0011-0100Z

Rev.1.00

Apr.16.2003

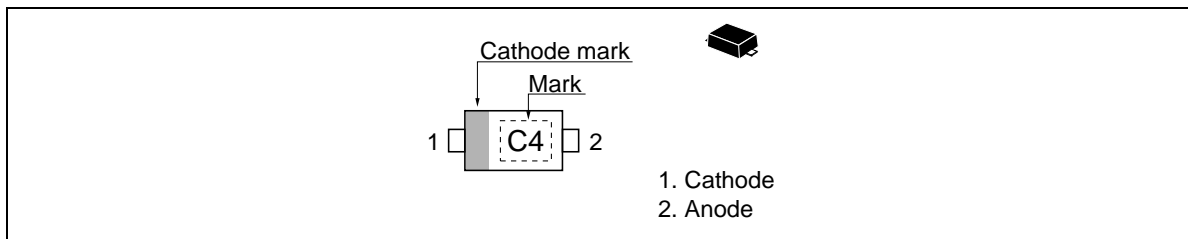
### Features

- Low forward voltage, Low capacitance and High detection sensitivity.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

### Ordering Information

Type No.	Laser Mark	Package Code
HSC285	C4	UFP

### Pin Arrangement



## HSC285

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### Absolute Maximum Ratings

( $T_a = 25^\circ\text{C}$ )

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	2	V
Average rectified current	$I_O$	5	mA
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{\text{stg}}$	-55 to +125	$^\circ\text{C}$

### Electrical Characteristics

( $T_a = 25^\circ\text{C}$ )

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_{F1}$	—	—	0.15	V	$I_F = 0.1 \text{ mA}$
	$V_{F2}$	—	—	0.27		$I_F = 1 \text{ mA}$
Capacitance	C	—	0.3	—	pF	$V_R = 1 \text{ V}$ , $f = 1 \text{ MHz}$
ESD-Capability *1	—	10	—	—	V	$C = 200 \text{ pF}$ , $R_L = 0 \Omega$ , Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion ;  $I_R > 100 \mu\text{A}$  at  $V_R = 0.5 \text{ V}$

Main Characteristic

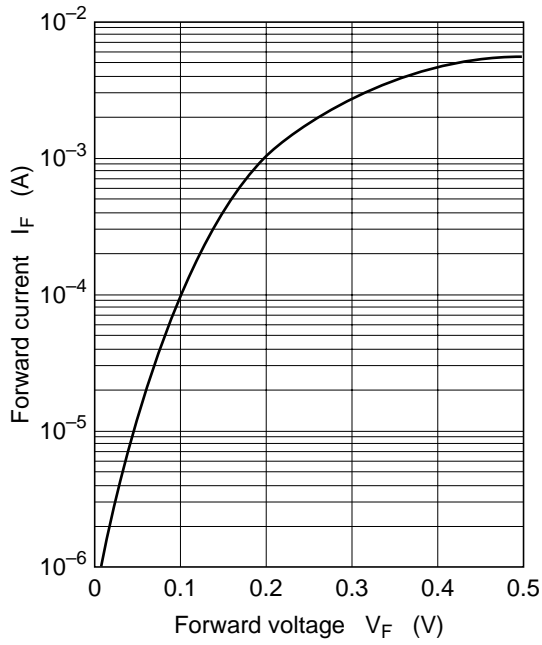


Fig.1 Forward current vs. Forward voltage

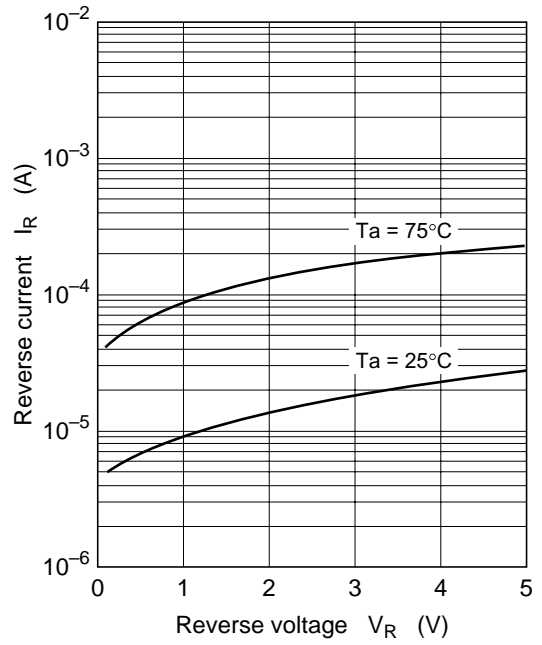


Fig.2 Reverse current vs. Reverse voltage

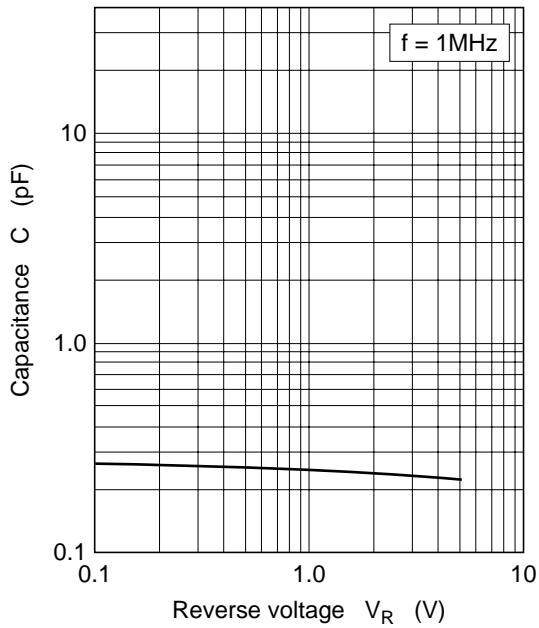
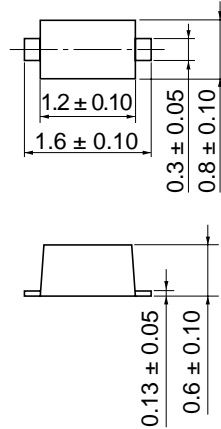


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2003  
Unit: mm



Package Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

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**Keep safety first in your circuit designs!**

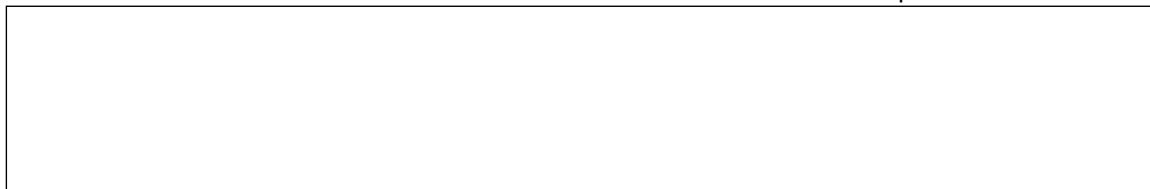
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